

### **REMARKS/**

The Office Action of January 21, 2003, has been carefully considered.

It is noted that claims 12 and 13 are rejected under 35 USC 103(a) over DE 92 18 985 in view of the patent to Morse.

Claims 14 and 22 are rejected under 35 USC 103(a) over the patent to Okada, et al. in view of XP-002128554, the patent to Honda and Morse.

Claims 17-20 and 23-24 are rejected under 35 USC 103(a) over Okada, et al., XP-002128554, Honda and Morse, and further in view of the patent to Vogt.

It is respectfully submitted that the claims presently on file differ essentially and in an unobvious, highly advantageous manner from the methods and constructions disclosed in the references.

Turning now to the references, and particularly to German reference 92 18 985, it can be seen that this reference discloses a laminator for producing a card.

The patent to Morse discloses a heat shielded press.

The Examiner combined these references in determining that claims 12 and 13 would be unpatentable over such a combination. The press of Morse has a heat shield which serves to prevent heat loss when the press is opened. Such a heat shield is not comparable with the features of the presently claimed invention. In the present invention the boundary region of the inserted template is enclosed during heating. In Morse, on the other hand, the heat shield elements 14 and 15 are separated from the heating elements 16 and 17 when the press is closed so that there is no or very little heat exchange possible to begin with. Furthermore, Morse provides no teaching of enclosing

a narrow boundary region of the inserted template so that quantities of heat flowing off are retained, blocked in, reflected in concentrated back onto the template. There is absolutely no mention by either of the references for such a step. To modify the teachings of DE 92 18 985 in view of the teachings of Morse, as suggested by the Examiner, can only be accomplished, if at all, by hindsight reconstruction of the present invention based upon the teachings of the present application. There is no motivation found in the teachings of either of these references for making the combination argued by the Examiner. As has previously been argued, without some acknowledgment of the problems associated with heat loss in the head regions during lamination it is respectfully submitted that there is nothing provided in the teachings of these references which would suggest the combination thereof as argued by the Examiner.

In view of these considerations it is respectfully submitted that the rejection of claims 12 and 13 under 35 USC 103(a) over a combination of the above-discussed references is overcome and should be withdrawn.

The patent to Okada, et al. discloses a method of and apparatus for producing a multi-layer ceramic board.

Reference XP-002128554 discloses a laminate board in which thermally insulated plates are attached to the edges of the heating plates in order to reduce the flow of heat from the edges of the heating plate and heat dispersion in the board.

The patent to Honda discloses a method of bonding veneer sheets and an apparatus therefore.

The patent to Morse, as discussed above, discloses a heat shielded press.

The Examiner combined these references in determining that claims 14 and 22 would be unpatentable over such a combination. Applicant respectfully submits that there is nothing in the

teachings of these references which would motivate one skilled in the art to make the combination of four references as argued by the Examiner to arrive at the presently claimed invention. Such a combination, if at all possible could only be accomplished by hindsight reconstruction of the invention based upon the teachings provided by the present application. There is nothing in the teachings of any of the references which acknowledges the problems being solved by the presently claimed invention and which would suggest a combination of features as argued by the Examiner to address these problems.

In view of these considerations it is respectfully submitted that the rejection of claims 14 and 22 under 35 USC 103(a) over a combination of the above-discussed references is overcome and should be withdrawn.

Relative to claims 17-20, 23 and 24, the Examiner adds yet another reference to his combination of Okada, XP-002128554, Honda and Morse. Applicant respectfully submits that there is nothing in the teachings of Vogt which would motivate one skilled in the art to modify any of the other cited references to arrive at the presently claimed invention.

In view of these considerations it is respectfully submitted that the rejection of claims 17-20, 23 and 24 under 35 USC 103(a) over a combination of the above-discussed references is overcome and should be withdrawn.


Reconsideration and allowance of the present application are respectfully requested.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee during the prosecution of this application is not paid, the Patent Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on April 21, 2003:

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Name of applicant, assignee or  
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Signature

April 21, 2003

Date of Signature

Respectfully submitted,



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